



Material Content Data Sheet



Sales Product Name				BSC050N04LS G		Issued		1. August 2018	
MA#				MA002262430					
Package				PG-TDSON-8-14		Weight*		119.12 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.426	1.20	1.20	11974	11974	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		327		
	non noble metal	iron	7439-89-6	0.778	0.65		6531		
wire	non noble metal	copper	7440-50-8	31.590	26.52	27.21	265195	272135	
	non noble metal	copper	7440-50-8	0.046	0.04	0.04	386	386	
	encapsulation	organic material	carbon black	1333-86-4	0.238	0.20		1999	
encapsulation	plastics	epoxy resin	-	7.382	6.20		61972		
	inorganic material	silicondioxide	60676-86-0	40.006	33.60	40.00	335848	399819	
leadfinish	non noble metal	tin	7440-31-5	1.243	1.04	1.04	10431	10431	
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	314	314	
solder	non noble metal	tin	7440-31-5	0.032	0.03		267		
	noble metal	silver	7440-22-4	0.040	0.03		334		
	non noble metal	lead	7439-92-1	1.518	1.27	1.33	12747	13348	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		179		
	non noble metal	iron	7439-89-6	0.428	0.36		3589		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.57	14.95	145735	149548	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	iron	7439-89-6	0.017	0.01		142		
*deviation	non noble metal	copper	7440-50-8	16.898	14.19	14.20	141860	142045	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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